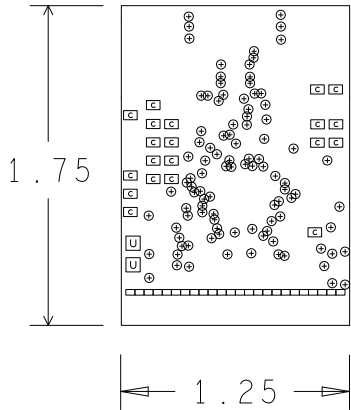


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE	14OCT2014	B.HURST

0.5 OZ. CU		0.012 INCH CORE	TOP	- SIGNAL
0.5 OZ. CU		0.011 INCH PREPREG	LAYER2	- GND PLANE
0.5 OZ. CU		0.010 INCH CORE	LAYER3	- SIGNAL
0.5 OZ. CU		0.011 INCH PREPREG	LAYER4	- SIGNAL
0.5 OZ. CU		0.012 INCH CORE	LAYER5	- PWR PLANE
0.5 OZ. CU			BOTTOM	- SIGNAL



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
	8.0	PLATED	101
	26.0	PLATED	24
	40.0	PLATED	20
	35.4	NON-PLATED	2

CATEGORY	DESCRIPTION
COPPER WEIGHT	0.5 OZ. ALL LAYERS
SOLDERMASK	BOTH SIDES WITH LPI GREEN OVER BARE COPPER
FINISHED HOLE TOLERANCES	PLATED: +/- .003 INCHES
	NON-PLATED: +/- .002 INCHES
	VIAS: + 0 INCHES, - SPECIFIED HOLE SIZE
DIMENSIONS	INCH
SUBSTRATE MATERIAL	370HR LAMINATE
FINISH	ENIG
PCB THICKNESS	0.062 +/- .004 INCHES
IPC SPECS	IPC-6012 TYPE 3 CLASS 2
SILKSCREEN	COMPONENT AND CIRCUIT SIDE WITH WHITE EPOXY INK. DO NOT USE INKJET PROCESS FOR SILKSCREEN.
VIAS	REMOVE SOLDERMASK FROM VIA IF ONE SIDE DOES NOT HAVE SOLDERMASK.
TEARDROPS	ADD TEARDROPS ON 5 MIL OR SMALLER TRACES.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ON: 2 PL DECIMALS + 3 PL DECIMALS + ANGLES + FRACTIONS +	SIGNATURES	DATE	MICROSEMI CORPORATION			
			ZL70251 WSN EVALUATION KIT			
			NODE100 BOARD			
			SIZE	FSCM NO	DWG NO	
			SCALE 1:1			SHEET 1 OF 1